



### **General Description**

The WSP4606C is the highest performance trench N-ch and P-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSP4606C meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

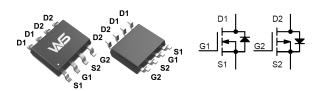
### **Product Summery**

BVDSS	RDSON	ID
20V	28mΩ	6.5A
-20V	55mΩ	-5.8A

### **Applications**

- ●MB/NB/UMPC/VGA
- DC-DC Power System
- Inverter

### **SOP-8 Pin Configuration**



#### **Absolute Maximum Ratings**

		Rating		
Symbol	Parameter	N-Ch	P-Ch	Units
$V_{DS}$	Drain-Source Voltage	20	-20	V
$V_{GS}$	Gate-Source Voltage	±10	±12	V
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current	6.5	-5.8	А
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current	3.8	-3.5	А
I <sub>DM</sub>	Pulsed Drain Current	28	-28	А
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation	1.5	1.5	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	-55 to 150	$^{\circ}$
TJ	Operating Junction Temperature Range	-55 to 150	-55 to 150	$^{\circ}$

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{thJA}$	Thermal Resistance Junction-Ambient		62.5	°C/W





## Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0 $V$ , $I_D$ =250 $u$ A	20			V
D	Static Drain-Source On-Resistance	$V_{GS}$ =4.5 $V$ , $I_D$ =3 $A$		28	35	· mΩ
R <sub>DS(ON)</sub>		$V_{GS}$ =2.5 $V$ , $I_D$ =2 $A$		32	40	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}$ = $V_{DS}$ , $I_D$ =250uA	0.4	0.72	1.2	٧
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V .			1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}$ =0V			±100	nA
Qg	Total Gate Charge			4.6		
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS}$ =15V, $V_{GS}$ =4.5V, $I_{D}$ =3A.		0.7		nC
$Q_{gd}$	Gate-Drain Charge			1.5		
T <sub>d(on)</sub>	Turn-On Delay Time			1.6		
Tr	Rise Time	V <sub>DD</sub> =10V,V <sub>GS</sub> =4.5V,R <sub>G</sub> =3.3		42		no
$T_{d(off)}$	Turn-Off Delay Time	Ω, I <sub>D</sub> =1A .		14		ns
T <sub>f</sub>	Fall Time			7		
C <sub>iss</sub>	Input Capacitance			310		
C <sub>oss</sub>	Output Capacitance	$V_{DS}$ =15V, $V_{GS}$ =0V,f=1MHz .		49		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			35		
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			3.6	Α
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =1A.			1.2	V





## P-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-20			V
D	Static Drain-Source On-Resistance	$V_{GS}$ =-4.5V , $I_D$ =-5A		55	80	mΩ
R <sub>DS(ON)</sub>		$V_{GS}$ =-2.5 $V$ , $I_D$ =-3 $A$		75	100	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}$ = $V_{DS}$ , $I_D$ =-250uA	-0.4	-0.60	-1.2	V
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =-20 $V$ , $V_{GS}$ =0 $V$ , $T_J$ =25 $^{\circ}$ C			1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 12V$ , $V_{DS}$ = $0V$			±100	nA
$Q_g$	Total Gate Charge			10.1		
$Q_gs$	Gate-Source Charge	$V_{DS}$ =-10V, $V_{GS}$ =-4.5V, $I_{D}$ =-3A.		1.21		nC
$Q_{gd}$	Gate-Drain Charge			2.46		
T <sub>d(on)</sub>	Turn-On Delay Time			5.6		
Tr	Rise Time	$V_{DD}$ =-10V, $V_{GS}$ =-4.5V , $R_{G}$ =3 $\Omega$		32.2		no
$T_{d(off)}$	Turn-Off Delay Time	, I <sub>D</sub> =-3A .		45.6		ns
T <sub>f</sub>	Fall Time			29.2		
C <sub>iss</sub>	Input Capacitance			677		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =-10V,V <sub>GS</sub> =0V , f=1MHz.		82		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			73		
Is	Continuous Source Current	T <sub>A</sub> =25°C			-3.0	Α
V <sub>SD</sub>	Diode Forward Voltage	I <sub>SD</sub> = -1A , V <sub>GS</sub> =0V.			-1.2	V

A: The value of ReJA is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with TA=25°C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The current rating is based on the t≤ 10s junction to ambient thermal resistance rating.



### **N-Channel Typical Characteristics**

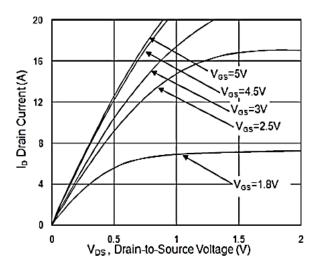


Fig.1 Typical Output Characteristics

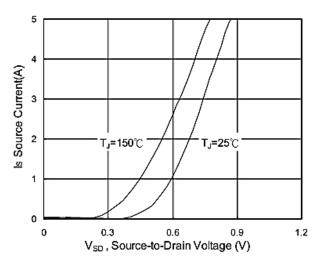


Fig.3 Source Drain Forward Characteristics

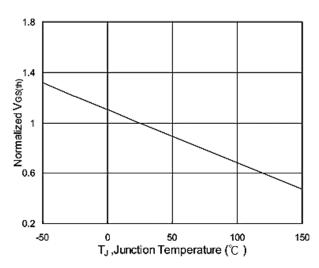


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

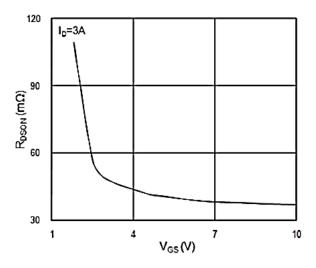


Fig.2 On-Resistance vs. G-S Voltage

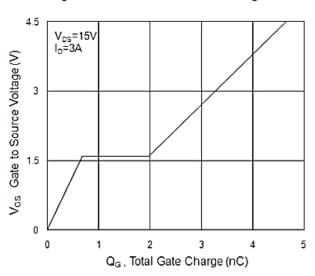


Fig.4 Gate-Charge Characteristics

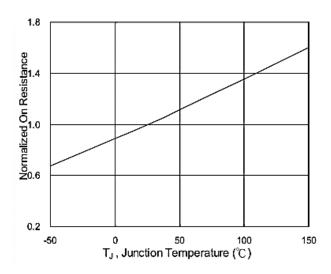
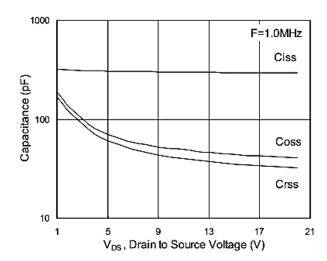


Fig.6 Normalized RDSON vs. TJ





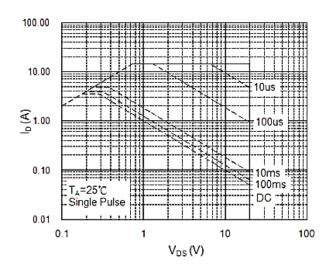


Fig.7 Capacitance

Fig.8 Safe Operating Area

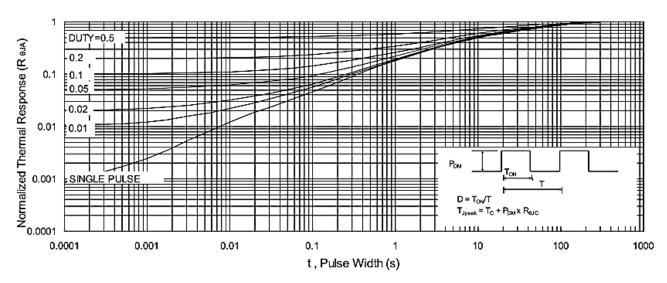
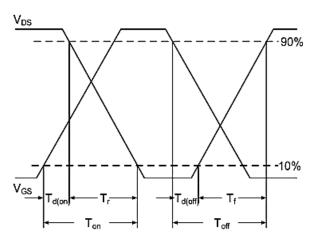


Fig.9 Normalized Maximum Transient Thermal Impedance





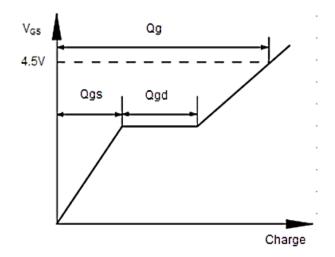


Fig.11 Gate Charge Waveform



### **P-Channel Typical Characteristics**

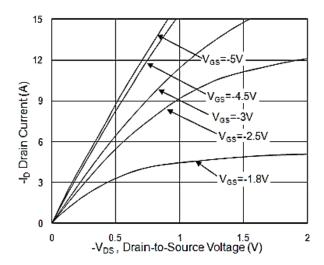


Fig.1 Typical Output Characteristics

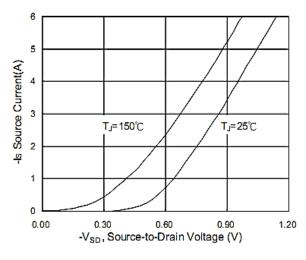


Fig.3 Forward Characteristics Of Reverse

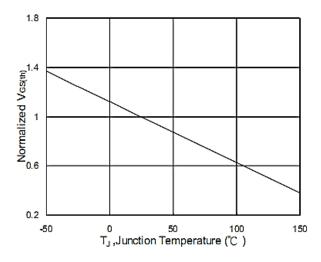


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

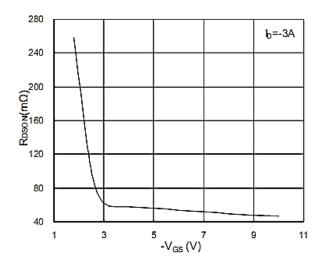


Fig.2 On-Resistance vs. Gate-Source

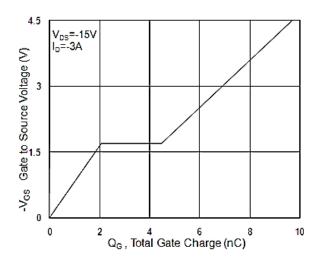


Fig.4 Gate-Charge Characteristics

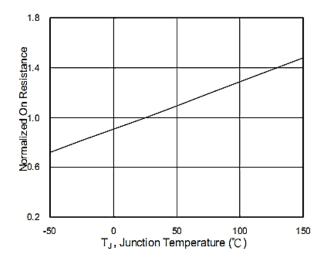
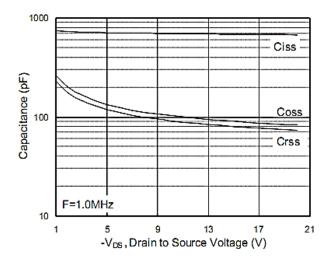


Fig.6 Normalized RDSON vs. TJ





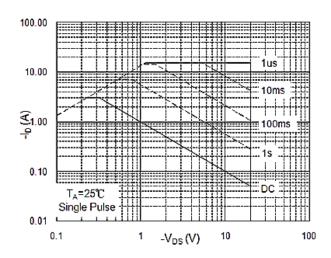


Fig.7 Capacitance

Fig.8 Safe Operating Area

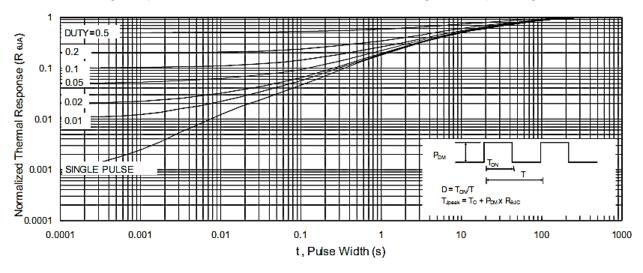
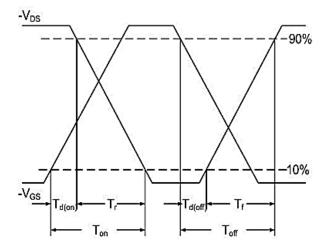
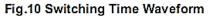


Fig.9 Normalized Maximum Transient Thermal Impedance





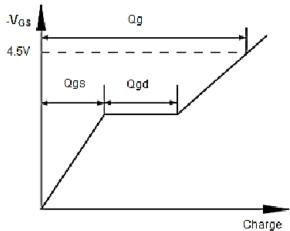


Fig.11 Gate Charge Waveform



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DMN1017UCP3-7 EFC2J004NUZTDG P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 DMC2700UDMQ-7 DMN2080UCB4-7
DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 IPS60R360PFD7SAKMA1
DMN2990UFB-7B SSM3K35CT,L3F IPLK60R1K0PFD7ATMA1 2N7002W-G MCAC30N06Y-TP IPWS65R035CFD7AXKSA1
MCQ7328-TP SSM3J143TU,LXHF DMN12M3UCA6-7 PJMF280N65E1\_T0\_00201 PJMF380N65E1\_T0\_00201
PJMF280N60E1\_T0\_00201 PJMF600N65E1\_T0\_00201 PJMF900N65E1\_T0\_00201